

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMV761MA	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 125	LMV76 1MA
LMV761MA/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 1MA
LMV761MA/NOPB.A	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 1MA
LMV761MAX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 1MA
LMV761MAX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 1MA
LMV761MF	Obsolete	Production	SOT-23 (DBV) 6	-	-	Call TI	Call TI	-40 to 125	C22A
LMV761MF/NOPB	Active	Production	SOT-23 (DBV) 6	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C22A
LMV761MF/NOPB.A	Active	Production	SOT-23 (DBV) 6	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C22A
LMV761MFX	Obsolete	Production	SOT-23 (DBV) 6	-	-	Call TI	Call TI	-40 to 125	C22A
LMV761MFX/NOPB	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C22A
LMV761MFX/NOPB.A	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C22A
LMV762MA	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 125	LMV7 62MA
LMV762MA/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV7 62MA
LMV762MA/NOPB.A	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV7 62MA
LMV762MAX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV7 62MA
LMV762MAX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV7 62MA
LMV762MM/NOPB	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C23A
LMV762MM/NOPB.A	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C23A
LMV762MMX	Obsolete	Production	VSSOP (DGK) 8	-	-	Call TI	Call TI	-40 to 125	C23A
LMV762MMX/NOPB	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C23A
LMV762MMX/NOPB.A	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	C23A

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMV762QMA/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 2QMA
LMV762QMA/NOPB.A	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 2QMA
LMV762QMAX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 2QMA
LMV762QMAX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV76 2QMA
LMV762QMM/NOPB	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	C32A
LMV762QMM/NOPB.A	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C32A
LMV762QMMX/NOPB	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	C32A
LMV762QMMX/NOPB.A	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C32A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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